Guest Editorial: Digitalbased and digitalintensive analog integrated circuits and systems

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Since traditional analogue and mixed-mode integrated circuits do not take advantage of scaling and are more and more often the bottleneck in terms of cost and performance of present-day integrated systems in nanoscale technologies [1], digital techniques are more and more often adopted in order to improve the performance of analogue and mixed-signal blocks [2, 3] or even to replace analogue functions with digital-based equivalents [4, 5]. This is particularly needed in order to meet the stringent requirements in terms of reconfigurability, area, power consumption and cost of emerging Internet of Things (IoT) applications [6] and biosensors [7]. In this context, the design of digital-assisted and digital-based integrated circuits is nowadays emerging as a very active area of research and this Special Issue aims at providing a vivid picture of some among the most recent advances in digital-based and digital-assisted integrated circuit design techniques across technologies and application domains. In particular, the contributions in this special issue covers the research areas of digital intensive techniques in power management integrated circuits (ICs9), high-speed data conversion and digital-assisted calibration.

Digital-based techniques in power management integrated circuits: The need for increased flexibility and reconfigurability is one of the main drivers leading to the introduction of digital-based and digital intensive solutions in power management ICs [8]. In this context, the Letter "Automatic power-stage partitioning method for reconfigurable SC DC–DC converters with reduced power-cell redundancy" by Xuchu Mu et al. [9] deals with fully integrated, digitally reconfigurable switched capacitor DC–DC converters and presents an automatic power-stage implementation methodology which enables reconfigurable, fine-grained voltage conversion ratios with efficient capacitance (and hence area) utilization and low complexity. In detail, the authors propose an algorithm which, starting from a given set of voltage conversion ratios and hardware constraints, generates a specific power-stage partitioning which attains a significant reduction in the number of sub-cells required for a fine-grained control of the voltage conversion ratio. The proposed methodology is applicable to both linear and binary SC converters. On the other hand, real-time reconfigurability and digital-based assistance can be valuable to tackle the limitations of specific DC–DC converter topologies. This clearly emerges from the Letter "Line-transient enhancement techniques for multi-path hybrid DC–DC converter with $<$1% output overshoot/undershoot" by Huihua Li et al. [10], which presents two transient enhancement techniques for multi-path switched-capacitor-inductor (MP-SCI) hybrid DC–DC converters intended to mitigate the line-transient-induced voltage coupling to the converter output, that is a specific limit of this topology. In essence, the proposed solutions prevent the direct line coupling through topology reconfiguration and power switch modulation. The proposed controller also features adaptive line transition detection and automatic flying-capacitor voltage balancing. From simulations, the output variation reduction during line transients can be more than 94% when compared with the existing solutions.

High-speed data conversion: Digital-based and digital-intensive techniques in radio-frequency (RF) integrated systems play a pivotal role towards the virtualization of critical RF subsystem, as demanded in versatile, multi-standard radio transceivers leveraging the software-defined radio (SDR) paradigm [11]. The applicability of such digital-centred paradigm is however closely related to the performance of high speed of data converters which operate at multi GS/s data rates leveraging time interleaving. In such converters the input buffer is very critical and can be easily a bottleneck in terms of power and performance. This important aspect is tackled in the paper "A 10GHz bandwidth 45.5dB SNDR buffer with local feedback in 45 nm CMOS" by Jie Wu et al. [12], which proposes a high-speed buffer with bandwidth expansion and slew-rate enhancement, targeting the requirements of time interleaved data converters operating at 20 GS/s. The new buffer is fabricated in 45 nm COMS process, and achieves 7.2 bit ENOB at 10GHz input frequency with consuming 20.4 mW.

Digital-assisted calibration: Even before the last developments of radical digital-in-concept analogue IC design approaches, digital techniques have been and are still a valuable asset to improve the performance of more traditional analogue and mixed-signal circuits [13]. In this framework the Letter "Digital calibration technique-based AC injection for continuous time sigma-delta converters" by Shengling Zhu et al. [14], presents an innovative digital calibration method based on AC signal injection for continuous-time sigma-delta analogue-to-digital converters. Compared to calibration techniques proposed in previous art, the new method does not require complex timing logic, processing or additional capacitors and does not adversely impact the dynamic performance of the converter. Furthermore, it is suitable to integration in nanoscale CMOS technologies.

Conclusion: The papers selected for this special issue present an interesting, although not exhaustive, picture of the present-day research on digital-based and digital intensive analogue and mixed signal techniques in power management ICs, high-speed data converters and digital-assisted calibration. In the next years, further developments related to the more and more pervasive development of the IoT and of next-gen biosensors are expected. Moreover, the development of new digital-based analogue processing approaches taking advantage of artificial intelligence (AI) and machine learning is expected. Last but not least, digital-based and digital intensive solutions is likely to provide answers to the open challenges related to the development of analogue and sensing functionalities in future CMOS technology nodes and non-CMOS emerging technologies (flexible semiconductors, spintronics, quantum computing).

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